

TechConnect Ventures
Sprint Challenge Brief:
Sustainable Films and Coatings for Paperboard

BACKGROUND

In support of several packaging companies, TechConnect Ventures is calling for Entries describing innovations and emerging approaches for sustainable films or coatings that can be applied to paperboard. Traditional films and coatings, such as those commonly added for barrier protection or to modify structural integrity, are often made of petroleum-based chemicals or negatively impact the recyclability of the finished paperboard product. To counteract this, the clients for this Sprint are interested in:

- Films or coatings produced from
 - Bio-sourced chemicals or
 - Raw materials obtained from recycled waste streams.
- Films or coatings that permit recycling via conventional methods

A film or coating that is both produced via a sustainable method and which permits standard recycling practices is of greatest interest to the clients however partial solutions remain within scope.

The goal of this sprint is to facilitate contact and interactions between the Sprint sponsor and active researchers or technology developers in this space. Submissions and novel concepts from individuals and organizations in academia and research are of significant interest, but all viable technology providers are invited to respond for potential commercial opportunities with the client.

AREAS OF INTEREST

Our clients are interested in all sustainably produced films and coatings or those that allow recycling via conventional methods. Relevant areas of interest include, but are not limited to:

- Bio-based polymers such as:
 - PHA
 - PLA
 - Bioplastics such as:
 - Bio-PET
 - Bio-propylene
 - Raw materials derived from waste streams via:
 - Chemical recycling
 - Enzymatic recycling
 - Thermal recycling
 - Films/coatings that permit conventional recycling approaches
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BUSINESS OPPORTUNITY FOR SOLVERS

All complete and eligible Entries will be included in our exclusive Innovation Opportunity Report that will be presented to the innovation-seeking clients and partners. Solvers with well-matched capabilities may be contacted directly by consortium members to discuss potential partnership opportunities. Top-rated Entries may also be invited to register or participate in an upcoming TechConnect Ventures event or pitch program.

PARTICIPATION RULES & GUIDELINES

1. You must complete the provided Submission webform on the Sprint Submission page.
2. You are encouraged to submit a short presentation or pitch deck. A template is available on the Submission page.
3. **DO NOT INCLUDE ANY INFORMATION MARKED CONFIDENTIAL, PROPRIETARY, SENSITIVE OR CLASSIFIED. SUBMISSIONS MARKED AS SUCH WILL NOT BE SHARED WITH CLIENTS.**

Solvers should to review the [Rules](#) and [Guidelines](#) provided on the Sprint page for details about participation, including submission criteria, eligibility information, and more.

QUESTIONS? Contact Executive Director, Nick Kacsandi at info@techconnectventures.com